Silicon NPN Epitaxial

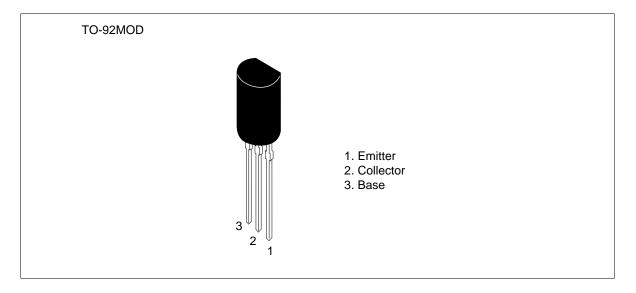
HITACHI

ADE-208-1139 (Z) 1st. Edition Mar. 2001

Application

- Low frequency power amplifier
- Complementary pair with 2SB738 and 2SB739

Outline



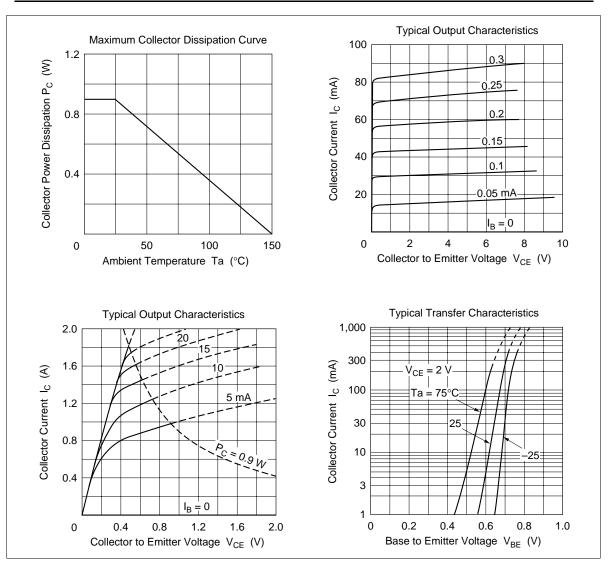


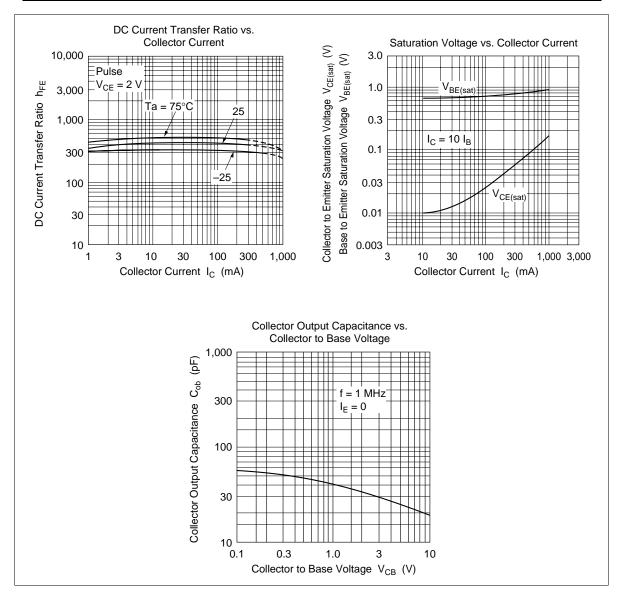
Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	2SD787	2SD788	Unit
Collector to base voltage	V _{CBO}	20	20	V
Collector to emitter voltage	V _{CEO}	16	20	V
Emitter to base voltage	V _{EBO}	6	6	V
Collector current	Ι _c	2	2	А
Collector power dissipation	Pc	0.9	0.9	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-50 to +150	°C

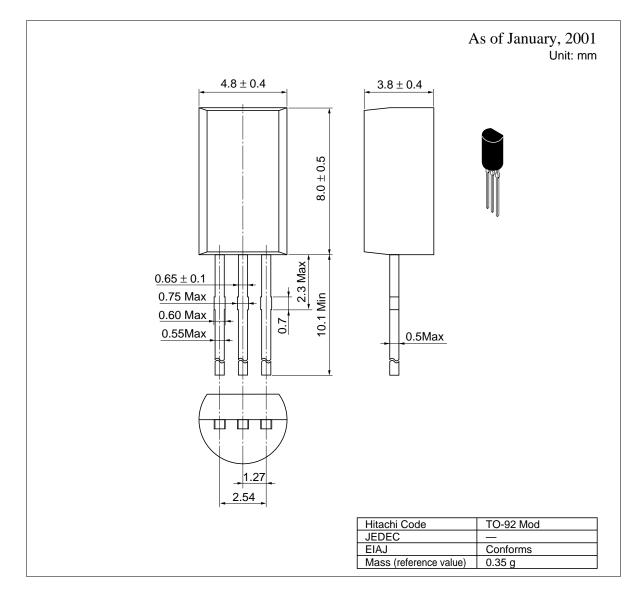
Electrical Characteristics (Ta = 25° C)

		2SD7	87		2SD788				
Item	Symbol	Min	Тур	Max	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	20	_	_	20	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\rm (BR)CEO}$	16	_	_	20	_	_	V	$I_c = 1 \text{ mA}, R_{\text{BE}} = \infty$
Emitter to base breakdown voltage	$V_{(\text{BR})\text{EBO}}$	6	_	_	6	_	_	V	$I_{\rm E} = 10 \ \mu {\rm A}, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	2	_		2	μΑ	$V_{\rm CB} = 16 \text{ V}, I_{\rm E} = 0$
Emitter cutoff current	I _{EBO}	—	—	0.2	—		0.2	μΑ	$V_{EB} = 6 V, I_{C} = 0$
DC current transfer ratio	h_{FE}^{*1}	100	—	800	100		800		$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 0.1 \text{ A}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.3	_	—	0.3	V	$I_{\rm c} = 1 \text{ A}, I_{\rm B} = 0.1 \text{ A}$
Gain bandwidth product	f _T	_	100	—	—	100	—	MHz	$V_{ce} = 2 V,$ $I_c = 10 mA$
Collector output capacitance	Cob	_	20	—	—	20	—	pF	$V_{CB} = 10 \text{ V}, \text{ I}_{E} = 0,$ f = 1 MHz
Note: 1. The 2SD787	and 2SD7	'88 are	groupe	ed by h	FE as fo	llows.			
B C	D		Е						
100 to 200 160 to 32	0 250 t	o 500	400	to 800	_				





Package Dimensions



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